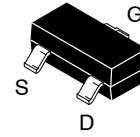


# Switch, N-Channel

## MMBF4093



SOT-23  
CASE 318-08

Note: Source & Drain are interchangeable

### Features

- This Device is Designed for Low Level Analog Switching Applications, Sample and Hold Circuits and Chopper Stabilized Amplifiers.
- Sourced from Process 51.
- This is a Pb-Free and a Halide Free Device

### ABSOLUTE MAXIMUM RATINGS (Note 1), (Note 2)

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DG}$	Drain-Gate Voltage	40	V
$V_{GS}$	Gate-Source Voltage	-40	V
$I_{GF}$	Forward Gate Current	50	mA
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to + 150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

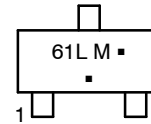
1. These ratings are based on a maximum junction temperature of  $150^\circ\text{C}$ .
2. These are steady-state limits. **onsemi** should be consulted on applications involving pulsed or low-duty cycle operations.

### THERMAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Max	Unit
$P_D$	Total Device Dissipation	350	mW
	Derate above $25^\circ\text{C}$	2.8	mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 3)	357	$^\circ\text{C}/\text{W}$

3. Device mounted on FR-4 PCB  $1.6'' \times 1.6'' \times 0.06''$ .

### MARKING DIAGRAM



61L = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MMBF4093	SOT-23 (Pb-Free)	3000 / Tape and Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

# MMBF4093

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Max	Unit
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### OFF CHARACTERISTICS

$V_{(BR)GSS}$	Gate–Source Breakdown Voltage	$I_G = 1 \mu\text{A}, V_{DS} = 0$	-40	-	V
$V_{GS(off)}$	Gate–Source Cut–Off Voltage	$V_{DS} = 20 \text{ V}, I_D = 1 \text{ nA}$	-1.0	-5.0	V
$I_{DGO}$	Drain–Gate Leakage Current	$V_{DG} = 20 \text{ V}, I_S = 0$ $V_{DG} = 20 \text{ V}, I_S = 0, T_A = 150^\circ\text{C}$	-	-200 -400	pA nA
$I_D(off)$	Drain Cutoff Leakage Current	$V_{DS} = 20 \text{ V}, V_{GS} = -6 \text{ V}$ $V_{DS} = 20 \text{ V}, V_{GS} = -6 \text{ V}, T_A = 150^\circ\text{C}$	-	200 400	pA nA

### ON CHARACTERISTICS

$I_{DSS}$	Zero–Gate Voltage Drain Current (Note 4)	$V_{DS} = 20 \text{ V}, I_{GS} = 0$	8	-	mA
$V_{DS(on)}$	Drain–Source On Voltage	$I_D = 2.5 \text{ mA}, V_{GS} = 0$	-	0.2	V
$r_{DS(on)}$	Drain–Source On Resistance	$I_D = 1 \text{ mA}, V_{GS} = 0$	-	80	$\Omega$

### SMALL SIGNAL CHARACTERISTICS

$r_{DS(on)}$	Drain–Source On Resistance	$V_{DS} = V_{GS} = 0, f = 1 \text{ kHz}$	-	80	$\Omega$
$C_{iss}$	Input Capacitance	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	-	16	pF
$C_{rss}$	Reverse Transfer Capacitance	$V_{DS} = -20 \text{ V}, f = 1.0 \text{ MHz}$	-	5	pF

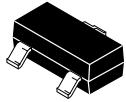
### SWITCHING CHARACTERISTICS

$t_{on}$	Turn–On Time	$I_{D(on)} = 3.0 \text{ mA}$	-	60	ns
$t_{off}$	Turn–Off Time	$V_{GS(off)} = 3.0 \text{ V}$	-	80	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 1\%$ .

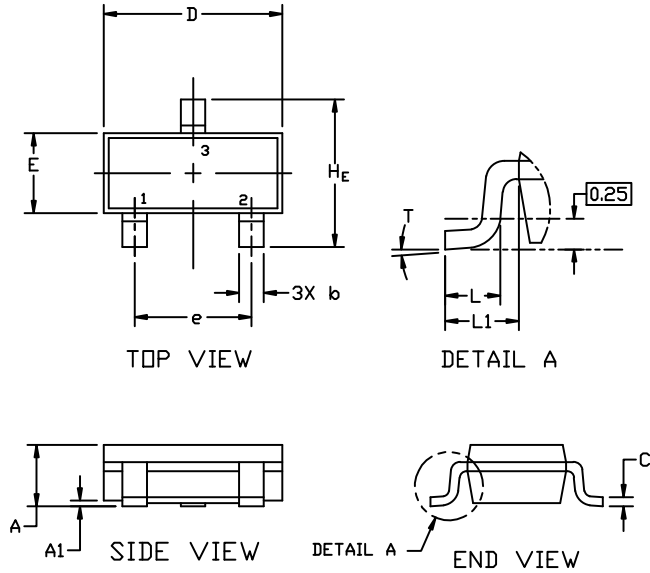
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**SOT-23 (TO-236)**  
CASE 318  
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1

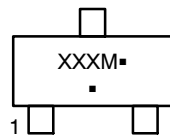


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

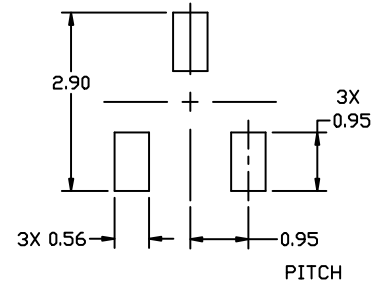
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H <sub>E</sub>	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



**RECOMMENDED MOUNTING FOOTPRINT**

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS



### SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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